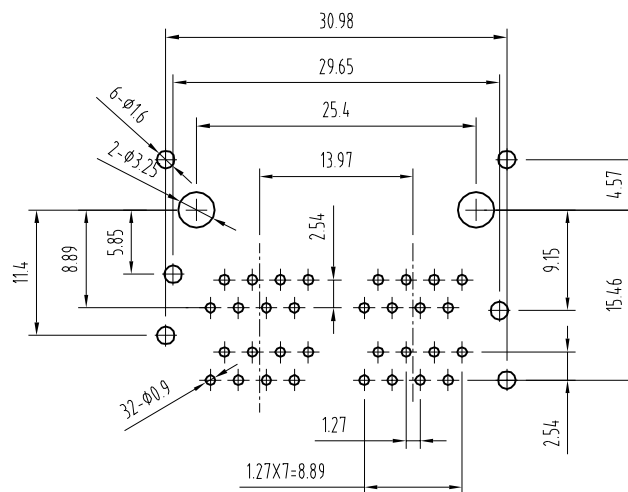
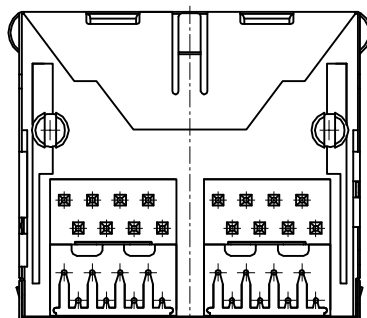
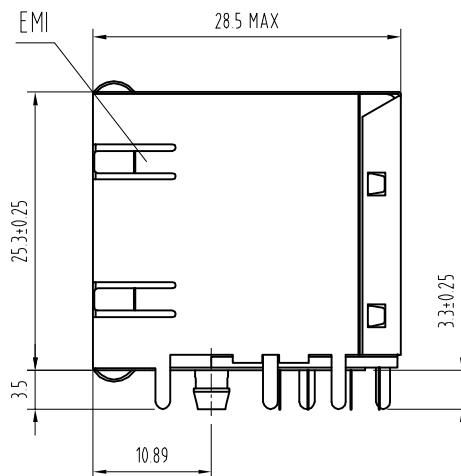
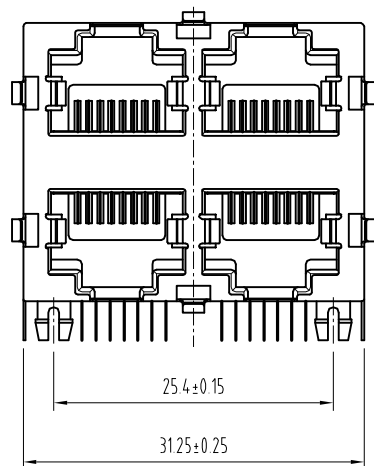




PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- | | |
|--------------------|---|
| 1.HOUSING MATERIAL | :GLASS FILLED POLYESTER UL94V-0. |
| 2.CONTACT MATERIAL | :PHOSPHOR BRONZE $\phi 0.46\text{mm}$. |
| 3.PLATING | :GOLD PLATING OVER NICKEL. |

ELECTRICAL:

- | | |
|--------------------------------------|------------------------------|
| 1.VOLTAGE RATING | :125 VAC RMS. |
| 2.CURRENT RATING | :1.5 AMP. |
| 3.CONTACT RESISTANCE | :30 MILLIOHMS MAX. |
| 4.INSULATION RESISTANCE | :500 MEGOHMS MIN @ 500V DC . |
| 5.DIELECTRIC WITHSTANDING RESISTANCE | :1000V AC RMS 50Hz. 1MIN. |

MECHANICAL:

- | | |
|----------------------------|------------------|
| 1.DURRABILITY | :750 CYCLES MIN. |
| 2.PCB RETENTION PRE-SOLDER | :1 LB MIN. |

ENVIRONMENTAL:

- | | |
|--------------|----------------|
| 1.STORAGE | : -40°C~+85°C |
| 2. OPERATION | : 0°C TO 70°C. |



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ45 2x2 90 ° DIP 无灯带弹	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW96-RJ45-285B
	APPROVED BY: 邱国夷	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-RJ17032010
SCALE:1:1	SIZE: A4		SHEET NO.	1 OF 1